IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Wu et al.

Title: Hot Carrier Circuit Reliability Stimulation

Application No.: 09/832,933 Filing Date: April 11, 2001

Examiner: Thomas H. Stevens Group Art Unit: 2123

Docket No.: BTAT.002US1 Conf. No.: 5253

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicants call the document listed on the enclosed Form PTO-1449 to the Examiner's attention in this patent application.

According to 37 C.F.R. 1.98(2)(ii), copies of the U.S. Patent Documents are not required and are therefore not enclosed. Copies of the listed Other Art are enclosed.

Citation of these documents shall not be construed as (1) an admission that the documents are prior art with respect to the invention or inventions claimed in this application, (2) a representation that a search has been made (other than as indicated by any cited document), or (3) an admission that the cited information is, or is considered to be, material to patentability as defined in § 1.56(b).

This information disclosure statement is submitted under 37 C.F.R. § 1.97(c). The Commissioner is authorized to charge \$180.00, any fee that may be required, or to credit any overpayment, against Deposit Account No. 502664.

Respectfully submitted,

Date

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U.S. Department of Commerce, Patent and Trademark				Atty. Docket No.			Application No.		
INFORMATION DISCLOSURE STATEMENT BY				BTAT.002US1	BTAT.002US1			09/832,933	
		APPLICANT		Applicant(s)			Conf. No.		
(Use several sheets if necessary) (Form PTO-1449)				Wu et al. Filing Date			5253 Art Group		
			U.S. F	atent Documents			10000		
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	1	Number 7,003,755	2/2006	Name Pang et al.	Class	Subclass	If Appro	priate	
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	3	6,209,122	03/2001	Jyu et al.					
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